LP M675

Mini TOPLED®









Applications

- Cluster, Button Backlighting
- Electronic Equipment

- Interior Illumination e.g. Ambient Map
- White Goods

Features:

- Package: white SMT package, colorless clear resin
- Chip technology: InGaAIP
- Typ. Radiation: 120° (Lambertian emitter)
- − Color: λ_{dom} = 560 nm (• pure green)
- Corrosion Robustness Class: 3B
- ESD: 2 kV acc. to ANSI/ESDA/JEDEC JS-001 (HBM)



Ordering Information		
Туре	Luminous Intensity $^{1)}$ $I_F = 30 \text{ mA}$ I_V	Ordering Code
LP M675-M2P1-25	22.4 56.0 mcd	Q65110A2399



LP M675

Maximum Ratings			
Parameter	Symbol		Values
Operating Temperature	T _{op}	min. max.	-40 °C 100 °C
Storage Temperature	T _{stg}	min. max.	-40 °C 100 °C
Junction Temperature	T _j	max.	125 °C
Forward current T _S = 25 °C	I _F	max.	40 mA
Surge Current t \leq 10 µs; D = 0.005 ; T _s = 25 °C	I _{FS}	max.	500 mA
Reverse voltage ²⁾ T _S = 25 °C	V_R	max.	12 V
ESD withstand voltage acc. to ANSI/ESDA/JEDEC JS-001 (HBM)	V_{ESD}		2 kV



Characteristics

 $I_F = 30$ mA; $T_S = 25$ °C

Parameter	Symbol		Values
Peak Wavelength	$\lambda_{\sf peak}$	typ.	562 nm
Dominant Wavelength 3)	λ_{dom}	min.	554 nm
I _F = 30 mA	dom	typ.	560 nm
		max.	566 nm
Spectral Bandwidth at 50% I _{rel,max}	Δλ	typ.	19 nm
Viewing angle at 50 % $\rm I_{\rm V}$	2φ	typ.	120 °
Forward Voltage 4)	V _F	min.	1.80 V
$I_F = 30 \text{ mA}$	•	typ.	2.00 V
		max.	2.40 V
Reverse current 2)	I _R	typ.	0.01 μΑ
V _R = 12 V		max.	10 µA
Temperature Coefficient of Peak Wavelength -10°C ≤ T ≤ 100°C	$TC_{\lambda peak}$	typ.	0.11 nm / K
Temperature Coefficient of Dominant Wavelength -10°C ≤ T ≤ 100°C	$TC_{\lambda dom}$	typ.	0.1 nm / K
Temperature Coefficient of Forward Voltage -10°C ≤ T ≤ 100°C	TC_{VF}	typ.	-2 mV / K
Real thermal resistance junction/ambient 5), 6)	R _{thJA real}	max.	480 K / W
Real thermal resistance junction/solderpoint 5)	R _{thJS real}	max.	230 K / W



Brightness Groups

Group	Luminous Intensity ¹⁾ $I_F = 30 \text{ mA}$ min. I_V	Luminous Intensity. 1) I _F = 30 mA max. I _v	Luminous Flux ⁷⁾ $I_F = 30 \text{ mA}$ typ. Φ_V
M2	22.4 mcd	28.0 mcd	80.0 mlm
N1	28.0 mcd	35.5 mcd	100.0 mlm
N2	35.5 mcd	45.0 mcd	120.0 mlm
P1	45.0 mcd	56.0 mcd	150.0 mlm

Wavelength Groups

Group	Dominant Wavelength 3)	Dominant Wavelength 3)
	$I_F = 30 \text{ mA}$	$I_F = 30 \text{ mA}$
min.		max.
	$\lambda_{\sf dom}$	λ_{dom}
2	554 nm	557 nm
3	557 nm	560 nm
4	560 nm	563 nm
5	563 nm	566 nm

Group Name on Label

Example: M2-2

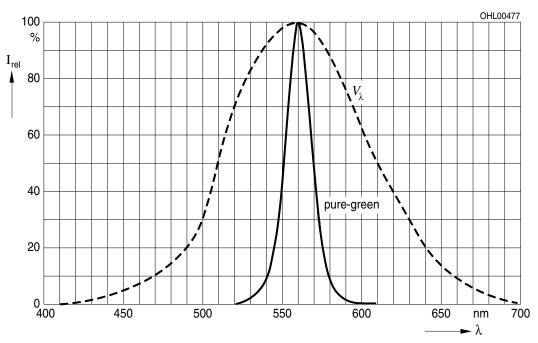
Brightness Wavelength

M2 2



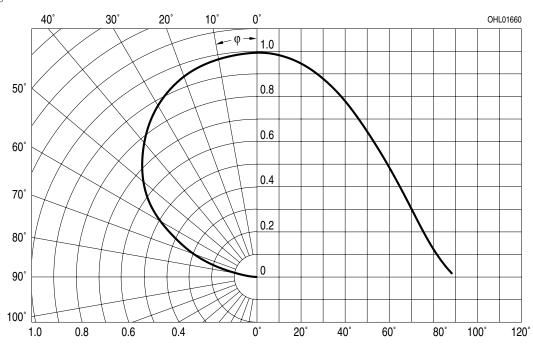
Relative Spectral Emission 7)

$$I_{rel}$$
 = f (λ); I_F = 30 mA; T_S = 25 °C



Radiation Characteristics 7)

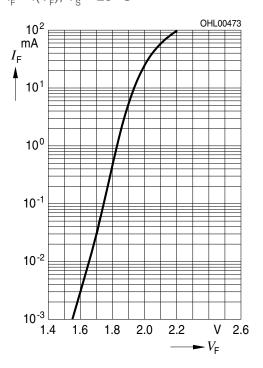
$$I_{rel} = f (\phi); T_S = 25 \, ^{\circ}C$$





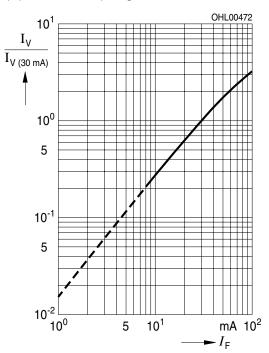
Forward current 7), 8)

$$I_F = f(V_F); T_S = 25 \, ^{\circ}C$$



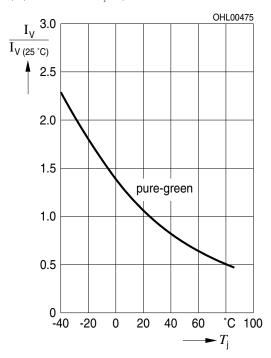
Relative Luminous Intensity 7), 8)

$$I_{v}/I_{v}(30 \text{ mA}) = f(I_{F}); T_{S} = 25 \text{ °C}$$



Relative Luminous Intensity 7)

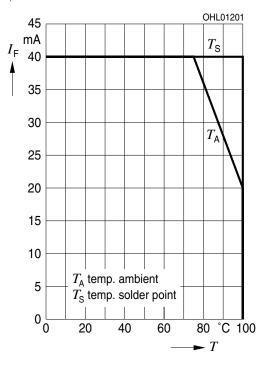
 $I_{v}/I_{v}(25 \text{ °C}) = f(T_{j}); I_{F} = 30 \text{ mA}$





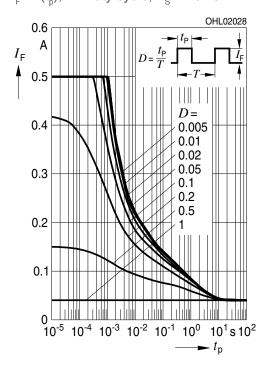
Max. Permissible Forward Current

 $I_{\scriptscriptstyle F} = f(T)$



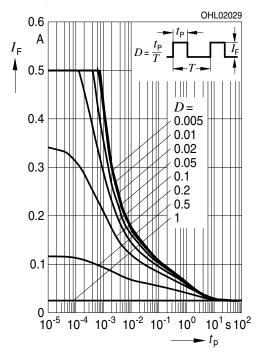
Permissible Pulse Handling Capability

 $I_{_{\rm F}}$ = f($t_{_{
m D}}$); D: Duty cycle; $T_{_{
m S}}$ = 25 °C

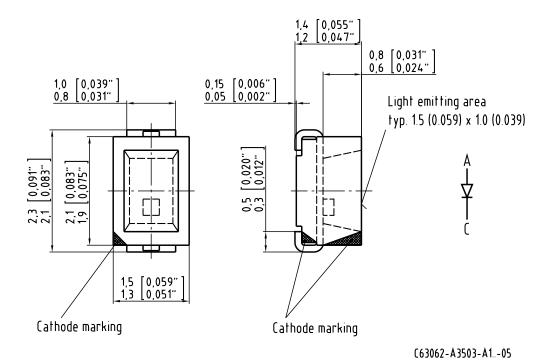


Permissible Pulse Handling Capability

 $I_{_{\rm F}}$ = f(t $_{_{
m D}}$); D: Duty cycle; $T_{_{
m S}}$ = 85 °C



Dimensional Drawing 9)



Approximate Weight: 7.0 mg

Package marking: Cathode

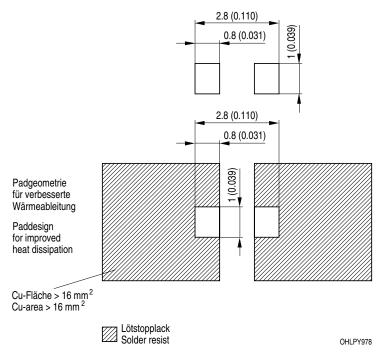
Corrosion test: Class: 3B

Test condition: 40° C / 90 % RH / 15 ppm H₂S / 14 days (stricter then IEC

60068-2-43)



Recommended Solder Pad 9)

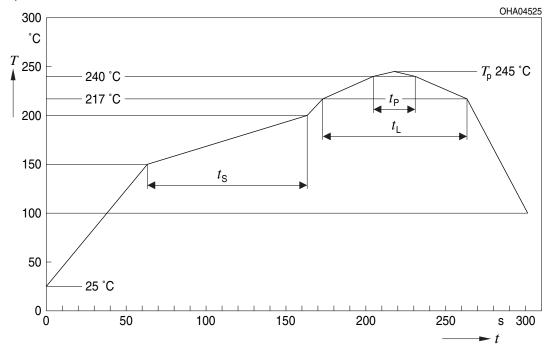


For superior solder joint connectivity results we recommend soldering under standard nitrogen atmosphere. Package not suitable for ultra sonic cleaning.



Reflow Soldering Profile

Product complies to MSL Level 2 acc. to JEDEC J-STD-020E

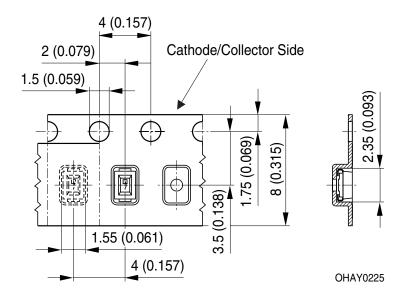


Profile Feature	Symbol	mbol Pb-Free (SnAgCu) Assembly			Unit
		Minimum	Recommendation	Maximum	
Ramp-up rate to preheat*) 25 °C to 150 °C			2	3	K/s
Time t_s T_{Smin} to T_{Smax}	t _s	60	100	120	S
Ramp-up rate to peak*) $T_{\rm Smax}$ to $T_{\rm P}$			2	3	K/s
Liquidus temperature	T_L		217		°C
Time above liquidus temperature	$t_{\scriptscriptstyle \perp}$		80	100	S
Peak temperature	T _P		245	260	°C
Time within 5 °C of the specified peak temperature T _P - 5 K	t _P	10	20	30	S
Ramp-down rate* T _P to 100 °C			3	6	K/s
Time 25 °C to T _P				480	S

All temperatures refer to the center of the package, measured on the top of the component * slope calculation DT/Dt: Dt max. 5 s; fulfillment for the whole T-range

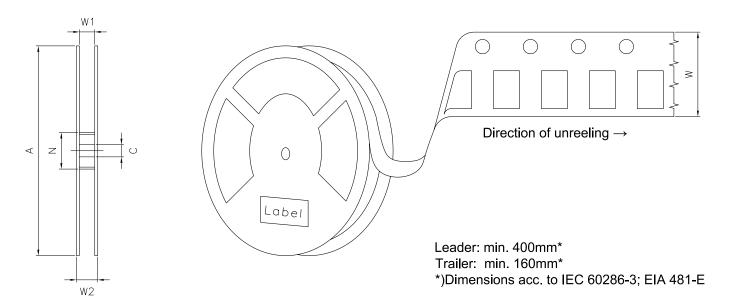


Taping 9)





Tape and Reel 10)



Reel dimensions [mm]

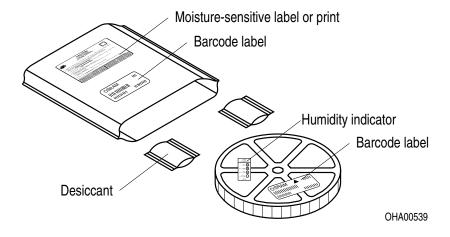
A	W	N_{\min}	W ₁	$W_{2\text{max}}$	Pieces per PU
180 mm	8 + 0.3 / - 0.1	60	8.4 + 2	14.4	3000



Barcode-Product-Label (BPL)



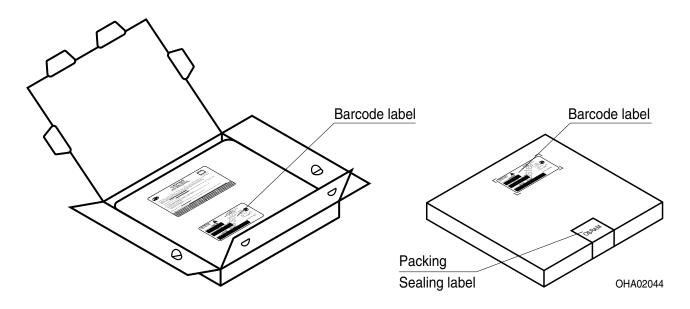
Dry Packing Process and Materials 9)



Moisture-sensitive product is packed in a dry bag containing desiccant and a humidity card according JEDEC-STD-033.



Transportation Packing and Materials 9)



Dimensions of transportation box in mm

Width	Length	Height	
200 ± 5 mm	195 ± 5 mm	30 ± 5 mm	



Type Designation System

S: T: Y: O: G: P: A:	_	blue super red true green yellow orange green pure green amber deep blue		color on dem	and blue and green and lagune	
	Light emitting diode					
L	A		M	6	7	6
4: t 6: f T: f V: f	hrough hole olded leads olded leads, Au-LF), w/o olded leads	improved corro TiO2 jetting and UX:3 w/ im .F), TiO2 jetting	proved corr			
	7: Cold	ant Type / Lens orless clear or w in encapsulation one (with or wit	vhite volumon)	e conversion		
		3: s 5: H 6: S B: H C: A F: T G: T K: II S: s 1: ir	Subcon: Sa nGaAIP low	GalP aAlP ninfilm InGaN) pphire) current GaN low currer	nt /	

Notes

The evaluation of eye safety occurs according to the standard IEC 62471:2006 (photo biological safety of lamps and lamp systems). Within the risk grouping system of this IEC standard, the LED specified in this data sheet fall into the class **exempt group (exposure time 10000 s)**. Under real circumstances (for exposure time, eye pupils, observation distance), it is assumed that no endangerment to the eye exists from these devices. As a matter of principle, however, it should be mentioned that intense light sources have a high secondary exposure potential due to their blinding effect. As is also true when viewing other bright light sources (e.g. headlights), temporary reduction in visual acuity and afterimages can occur, leading to irritation, annoyance, visual impairment, and even accidents, depending on the situation.

Subcomponents of this LED contain, in addition to other substances, metal filled materials including silver. Metal filled materials can be affected by environments that contain traces of aggressive substances. Therefore, we recommend that customers minimize LED exposure to aggressive substances during storage, production, and use. LEDs that showed visible discoloration when tested using the described tests above did show no performance deviations within failure limits during the stated test duration. Respective failure limits are described in the IEC60810.

For further application related informations please visit www.osram-os.com/appnotes



Disclaimer

Disclaimer

Language english will prevail in case of any discrepancies or deviations between the two language wordings.

Attention please!

The information describes the type of component and shall not be considered as assured characteristics. Terms of delivery and rights to change design reserved. Due to technical requirements components may contain dangerous substances.

For information on the types in question please contact our Sales Organization.

If printed or downloaded, please find the latest version on the OSRAM OS webside.

Packing

Please use the recycling operators known to you. We can also help you – get in touch with your nearest sales office.

By agreement we will take packing material back, if it is sorted. You must bear the costs of transport. For packing material that is returned to us unsorted or which we are not obliged to accept, we shall have to invoice you for any costs incurred.

Product safety devices/applications or medical devices/applications

OSRAM OS components are not developed, constructed or tested for the application as safety relevant component or for the application in medical devices.

In case Buyer - or Customer supplied by Buyer- considers using OSRAM OS components in product safety devices/applications or medical devices/applications, Buyer and/or Customer has to inform the local sales partner of OSRAM OS immediately and OSRAM OS and Buyer and /or Customer will analyze and coordinate the customer-specific request between OSRAM OS and Buyer and/or Customer.



Glossary

- Brightness: Brightness values are measured during a current pulse of typically 25 ms, with an internal reproducibility of ±8 % and an expanded uncertainty of ±11 % (acc. to GUM with a coverage factor of
- Reverse Operation: Reverse Operation of 10 hours is permissible in total. Continuous reverse operation is not allowed.
- 3) Wavelength: The wavelength is measured at a current pulse of typically 25 ms, with an internal reproducibility of ±0.5 nm and an expanded uncertainty of ±1 nm (acc. to GUM with a coverage factor of k =
- Forward Voltage: The forward voltage is measured during a current pulse of typically 8 ms, with an internal reproducibility of ±0.05 V and an expanded uncertainty of ±0.1 V (acc. to GUM with a coverage factor of k = 3).
- 5) **Thermal Resistance**: Rth max is based on statistic values (6σ).
- 6) Thermal Resistance: RthJA results from mounting on PC board FR 4 (pad size 16 mm² per pad)
- 7) Typical Values: Due to the special conditions of the manufacturing processes of LED, the typical data or calculated correlations of technical parameters can only reflect statistical figures. These do not necessarily correspond to the actual parameters of each single product, which could differ from the typical data and calculated correlations or the typical characteristic line. If requested, e.g. because of technical improvements, these typ. data will be changed without any further notice.
- 8) Characteristic curve: In the range where the line of the graph is broken, you must expect higher differences between single LEDs within one packing unit.
- 9) Tolerance of Measure: Unless otherwise noted in drawing, tolerances are specified with ±0.1 and dimensions are specified in mm.
- Tape and Reel: All dimensions and tolerances are specified acc. IEC 60286-3 and specified in mm.



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